Cient Code: QCO.130A



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ਾ਼ੇਂo the Director, U.S. Patent and

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ached original documents or copy thereof.

1. Name of conveying party: (List using letters or numbers for multiple parties) Chih-Wei Chiang Additional name(s) of conveying party(ies) attached? () Yes (X) No 3. Nature of conveyance: (X) Assignment () Security Agreement () Merger () Change of Name () Other: Execution Date: (List as in section 1 if multiple signatures) 19 December 2006	 Name and address of receiving party(ies): Name: QUALCOMM MEMS Technologies, Inc. Address: 5775 Morehouse Drive San Diego, California 92121 Additional name(s) of receiving party(ies) attached? () Yes (X) No US or PCT Application number(s) or US Patent number(s): (X) Patent Application No.: 11/646,059 Filing Date: December 27, 2006 	
	Additional numbers attached? () Yes (X) No	
 5. Party to whom correspondence concerning document should be mailed: Customer No. 20,995 Address: Knobbe, Martens, Olson & Bear, LLP 2040 Main Street, 14th Floor Irvine, CA 92614 Return Fax: (949) 760-9502 Attorney's Docket No.: QCO.130A 7. Total fee (37 CFR 1.21(h)): \$40 (X) Enclosed 	8. Deposit account number: 11-1410 Please charge this account for any additional fees which may be required, or credit any overpayment to this account.	
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct, and any attached copy is a true copy of the original document. Adeel S. Akhtar Name of Person Signing Signature Total number of pages including cover sheet, attachments and document: 2		
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ASSIGNMENT

WHEREAS, I, Chih-Wei Chiang, a Taiwan, ROC citizen, residing at 13F-1, No. 5, lane 73, Chin-Kuo Road section 3, Hsin-Chu city, Taiwan, R.O.C., has invented certain new and useful improvements in ALUMINUM FLUORIDE FILMS FOR MICROELECTROMECHANICAL SYSTEM APPLICATIONS for which I caused to be filed an application for Letters Patent in the United States; and we hereby authorize and request the attorneys of Knobbe, Martens, Olson & Bear, LLP, Customer No. 20,995, to insert here in parentheses (Application Number 1/646,051 filed 12.27.06) the filing date and application number of said application when known;

AND WHEREAS, QUALCOMM MEMS Technologies, Inc. (hereinafter "ASSIGNEE"), a Delaware corporation, with its principal place of business at 5775 Morehouse Drive, San Diego, California 92121, U.S.A, desires to acquire the entire right, title, and interest in and to the said improvements and the said Application.

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, we, the said inventors, do hereby acknowledge that we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, the entire right, title, and interest throughout the world in, to and under the said improvements, and the said application and all provisional application(s) to which said Application claims, or is entitled to claim, priority, and all divisions, renewals and continuations thereof, and all Letters Patent of the United States which may be granted thereon and all reissues and extensions thereof, and all rights of priority under International Conventions and applications for Letters Patent which may hereafter be filed for said improvements in any country or countries foreign to the United States, and all Letters Patent which may be granted for said improvements in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and we hereby authorize and request the Commissioner of Patents of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said improvements to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I DO HEREBY sell, assign, transfer, and convey to the said ASSIGNEE, its successors, legal representatives, and assigns all claims for damages and all remedies arising out of any violation of the rights assigned hereby that may have accrued prior to the date of assignment to the said ASSIGNEE, or may accrue hereafter, including, but not limited to, the right to sue for, collect, and retain damages for past infringements of the said Letters Patent before or after issuance.

AND I HEREBY covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said improvements, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing and reissue applications, make all rightful oaths and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said improvements in all countries.

	IN TESTIMONY WHEREOF, I hereunt	o set my hand and seal this 19 day of December, 2006
		Chih-Wei Chiang
		Chih-Wei Chiang
	IN TESTIMONY WHEREOF, acknow, 20	ledged by QUALCOMM MEMS Technologies, Inc. this day of
		QUALCOMM MEMS Technologies, Inc.
		Name:
135907	112006	Title:

RECORDED: 02/26/2007

PATENT REEL: 018973 FRAME: 0386